



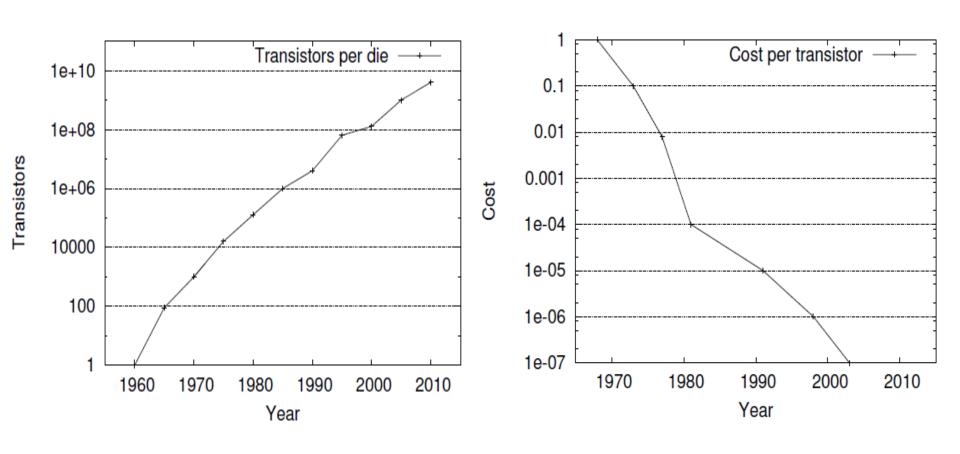
Advanced Computer Architecture System-on-Chip

By Amirreza Hosseini Dr. Farbeh

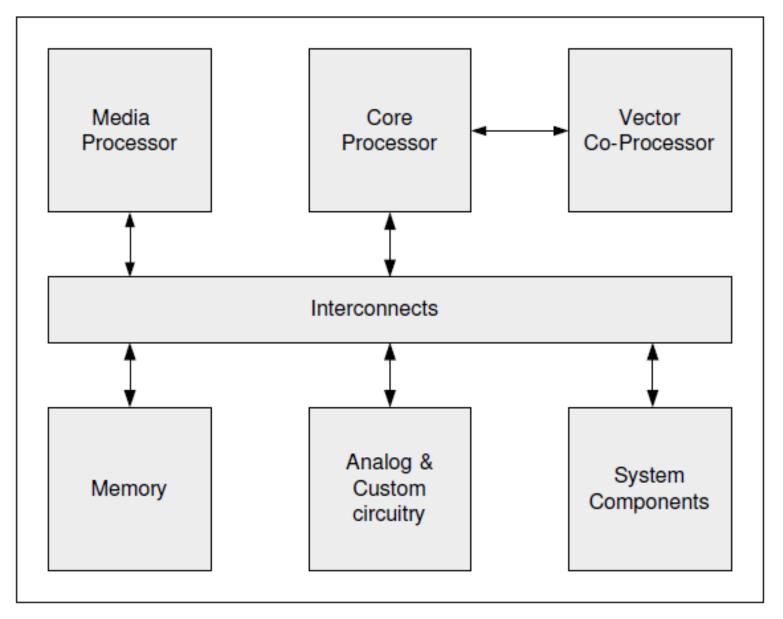
SOC architecture and design

- system-on-chip (SOC)
 - processors: become components in a system
- SOC covers many topics
 - processors, cache, memory, interconnect, design tools
- need to know
 - user view: variety of processors
 - basic information: technology and tools
 - processor internals: effect on performance
 - storage: cache, embedded and external memory
 - interconnect: buses, network-on-chip
 - evaluation: processor, cache, memory, interconnect
 - advanced: specialized processors, reconfiguration
 - design productivity: system modelling, design exploration

System on a Chip: driven by semiconductor advances



Basic system-on-chip model

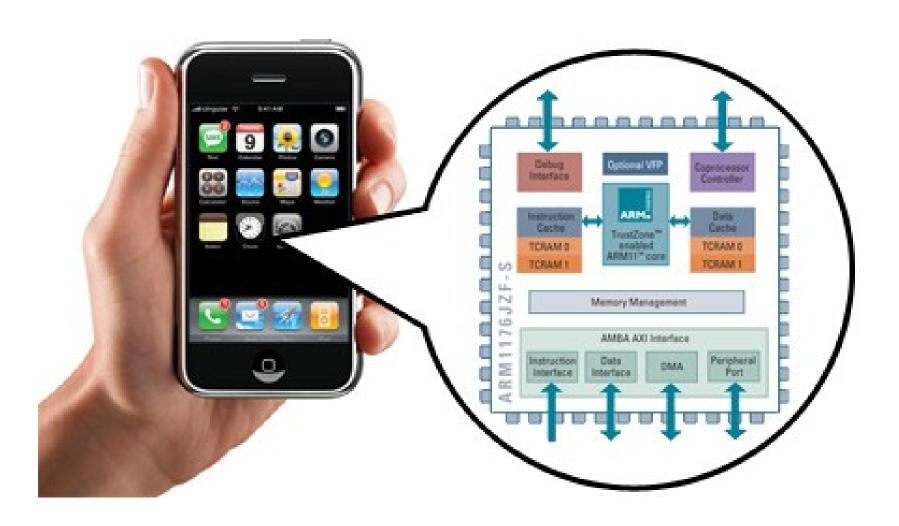


SOC vs processors on chip

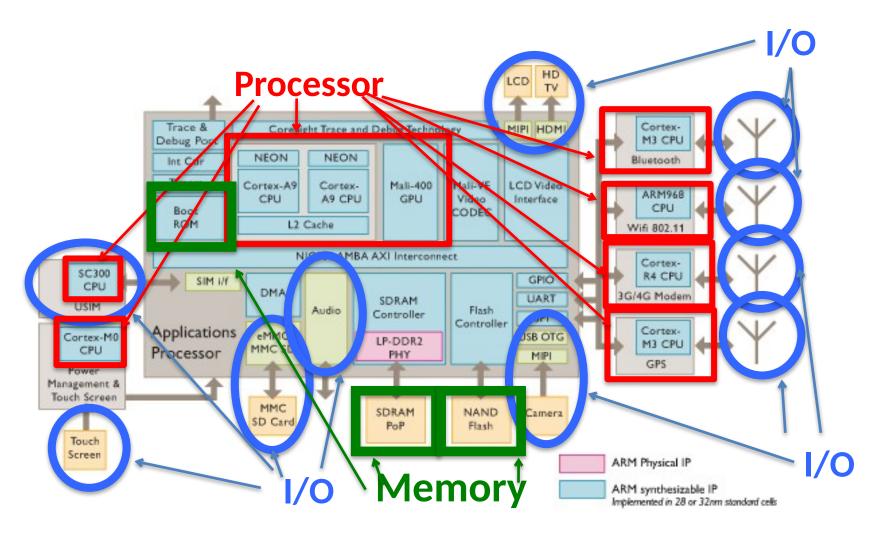
- with lots of transistors, designs move in 2 ways:
 - complete system on a chip
 - multi-core processors with lots of cache

	System on chip	Processors on chip
processor	multiple, simple, heterogeneous	few, complex, homogeneous
cache	one level, small	2-3 levels, extensive
memory	embedded, on chip	very large, off chip
functionality	special purpose	general purpose
interconnect	wide, high bandwidth	often through cache
power, cost	both low	both high
operation	largely stand-alone	need other chips

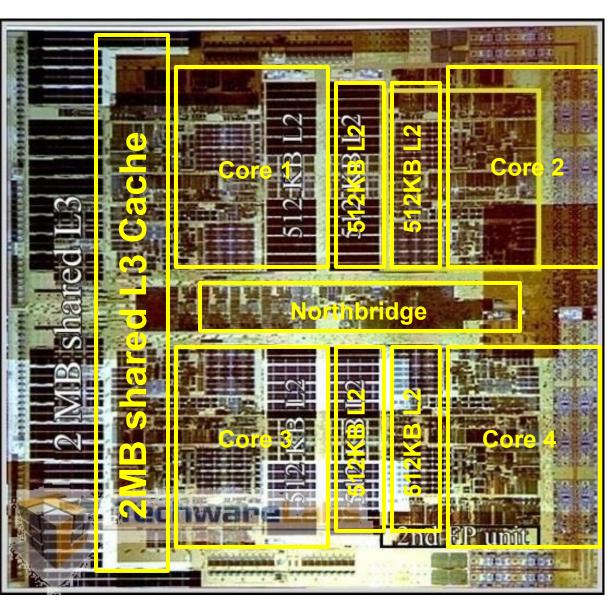
iPhone: has System-on-Chip



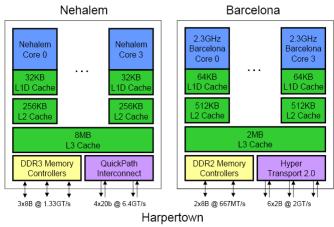
iPhone SOC

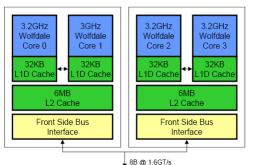


AMD's Barcelona Multicore



- 4 out-of-order cores
- 1.9 GHz clock rate
- 65nm technology
- 3 levels of caches
- integrated Northbridge

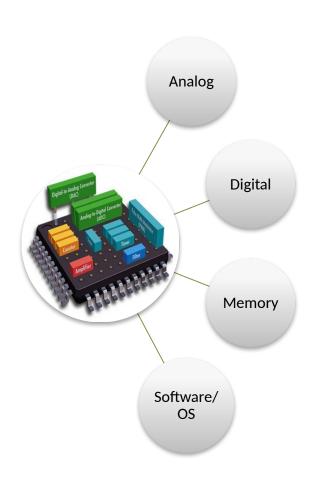


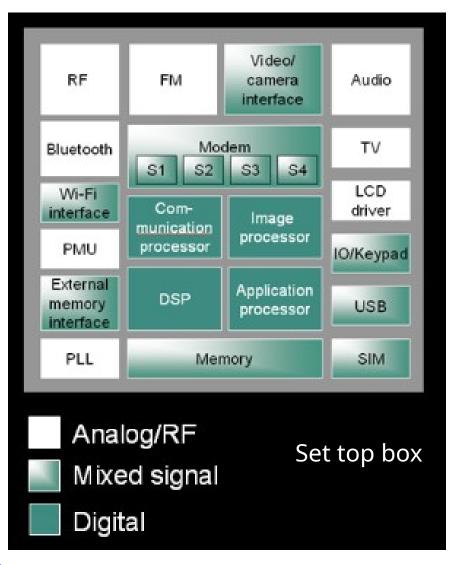


Why System on Chip



System of Chip Components

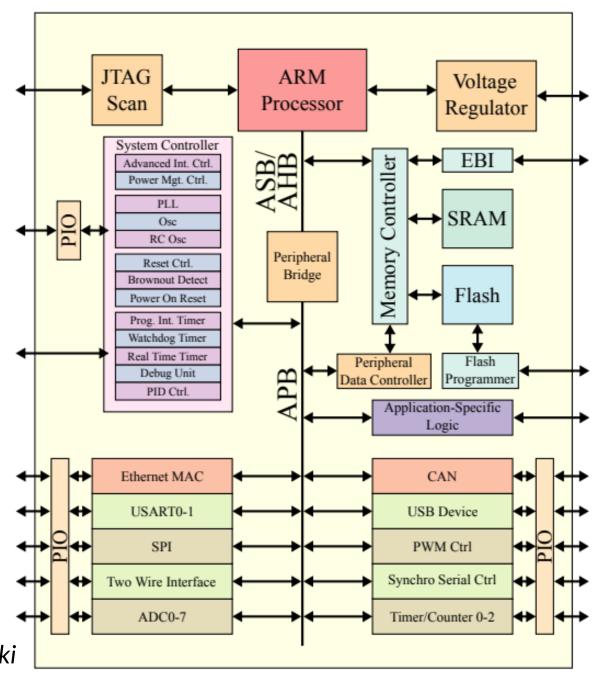




SoC Hardware Architecture

Often used in embedded application.

How to implement an application on a HW platform executing some SW programs?



source: wiki

SOC design: key ideas

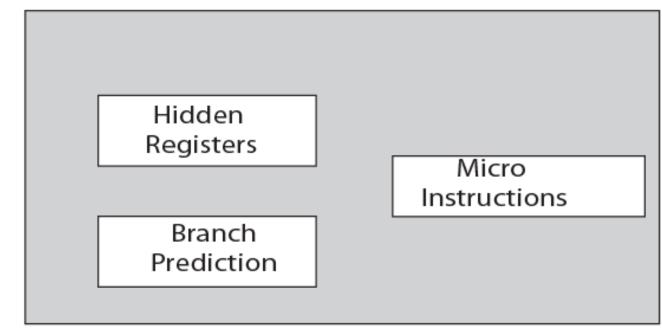
- to design and evaluate an SOC, designers need to understand:
 - its components: processors, memory, interconnect
 - applications that it targets
- SOC economics heavily dependent on:
 - costs: initial design, marginal production
 - volume: applicability, lifetime
- reducing design complexity
 - Intellectual Property (IP)
 - reconfigurable technology

SOC processors

- usually a mix of special and general purpose (GP)
 - can be proprietary design or purchased IP
- commonly GP processor is purchased IP
 - includes OS and compiler support
- GP processor optimized for an application
 - additional instructions
 - vector units

Architecture Data Paths Control Registers Instruction Set ALU Memory

Implementation



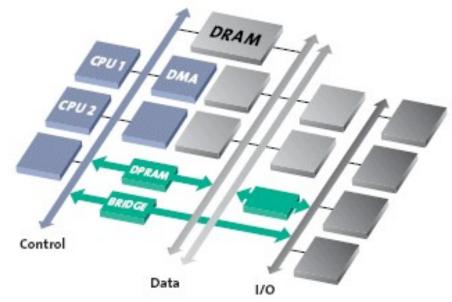
Research

- Interconnect topologies
 - e.g. bus
- Hybrid modules, Analog, Digital, ASIP, i.e. integration of mixed signal elements.

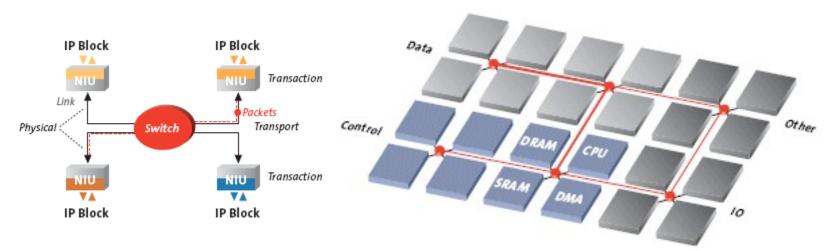
Mixed Signal (integrated analog blocks such as A to D and D to A converters, phase-locked loops, and adaptive filters.)

- On chip communication, power, switching delay, performance such as throughput.
- Hardware software co design for reuse.

Traditional architecture



Current NOC (arteris.com)



Interconnect topologies

- Bus
- Star
- Cube
- Tree
- Spin

Some processors for SOCs

SOC	Basic ISA	Processor description
Freescale c600: signal processing	PowerPC	Superscalar with vector extension
ClearSpeed CSX600: general	Proprietary	Array processor with 96 processing elements
PlayStation 2: gaming	MIPS	Pipelined with 2 vector coprocessors
ARM VFP11: general	ARM	Configurable vector coprocessor

Processor types: overview

Processor type	Architecture / Implementation approach
SIMD	Single instruction applied to multiple functional units
Vector	Single instruction applied to multiple pipelined registers
VLIW	Multiple instructions issued each cycle under <i>compiler</i> control
Superscalar	Multiple instructions issued each cycle under <i>hardware</i> control

Adding instructions

- additional instructions to support specialized resources
 - exception: superscalar, with hardware control
- instructions can be added to base processor for coprocessor control
 - VLIW: Very Large Instruction Word
 - Array
 - Vector

Sequential and parallel machines

- basic single stream processors
 - pipelined: basic sequential
 - superscalar: transparently concurrent
 - VLIW: compiler generated concurrency
- multiple stream
 - array processors
 - vector processors
- multiprocessors

Sequential processors

- operation
 - generally transparent to sequential programmer
 - appear as in order instruction execution
- pipeline processor
 - execution in order
 - limited to one instruction execution / cycle
- superscalar processor
 - multi instructions / cycle, managed by hardware
- VLIW
 - multi op execution / cycle, managed by compiler

PCI serial and parallel

PCI Express PCI Comparison Device 1 Device 2 SWITCH **PCI Express Serial Connection** BUS Device 3 Device 1 Device 2 **Parallel Connection** BUS

http://computer.howstuffworks.com/pci-express1.htm

System Chip – Advantages and Issues

Advantages

- Easily reprogrammable, reuse of Intellectual property.
- Lower chip area, reduce in silicon
- Low cost

Issues

- On chip routing and timing.
- Limitations of On chip resources

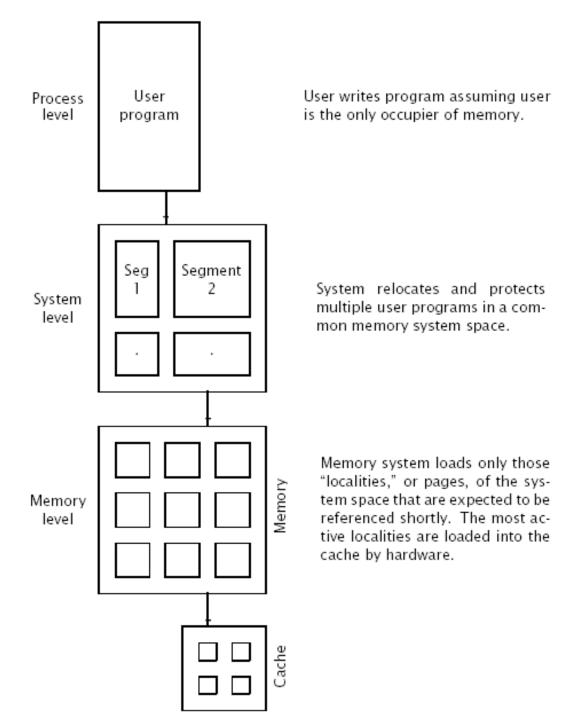
Parallel processors

- execution managed by programmer
- array processors
 - single instruction stream, multiple data streams: SIMD
- vector processors
 - SIMD
- multiprocessors
 - multiple instruction streams, multiple data streams:
 MIMD

Memory and addressing

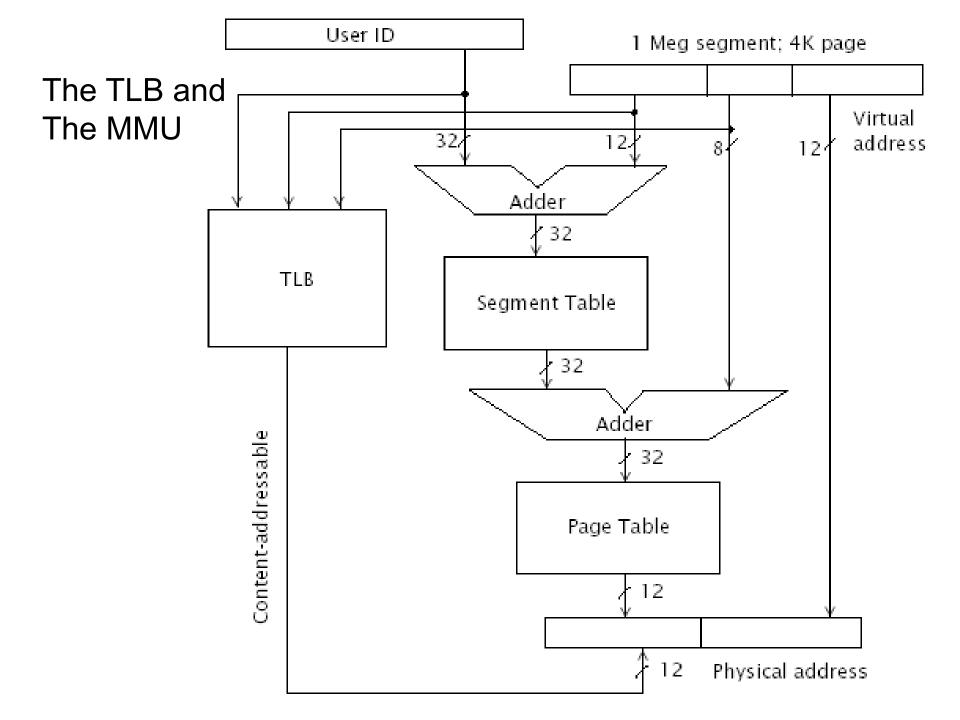
- many SOC memory designs use simple embedded memory
 - a single level cache
 - real (rather than virtual) addressing
- as SOC become more complex
 - their designs are expected to use more complex memory and addressing configurations

Three levels of addressing



User view of memory: addressing

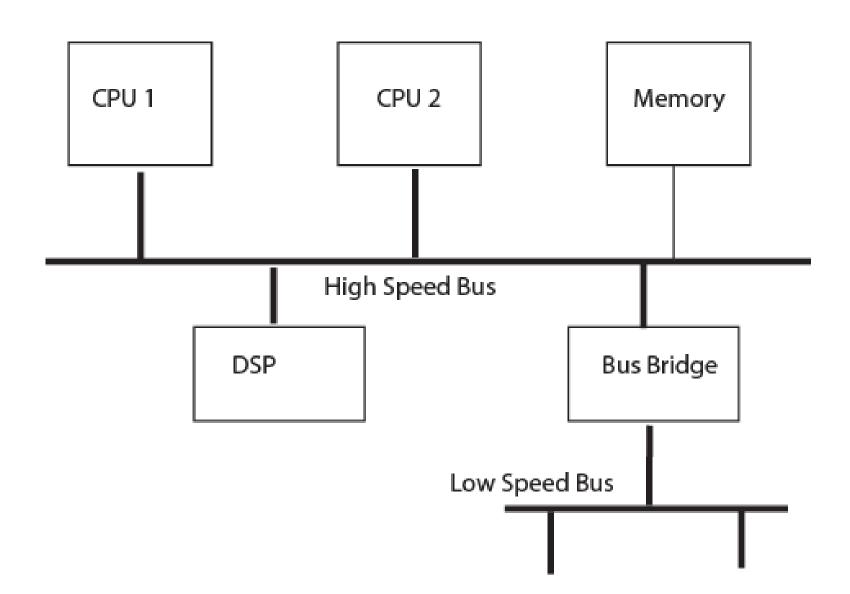
- a program: process address (offset + base + index)
 - virtual address: process address + process id
- a process: assigned a segment base and bound
 - system address: segment base + process address
- pages: active localities in main/real memory
 - virtual address: translated by table lookup to real address
 - page miss: virtual pages not in page table
- TLB (translation look-aside buffer): recent translations
 - TLB entry: corresponding real and (virtual, id) address
- a few hashed virtual address bits address TLB entries
 - if virtual, id = TLB (virtual, id) then use translation



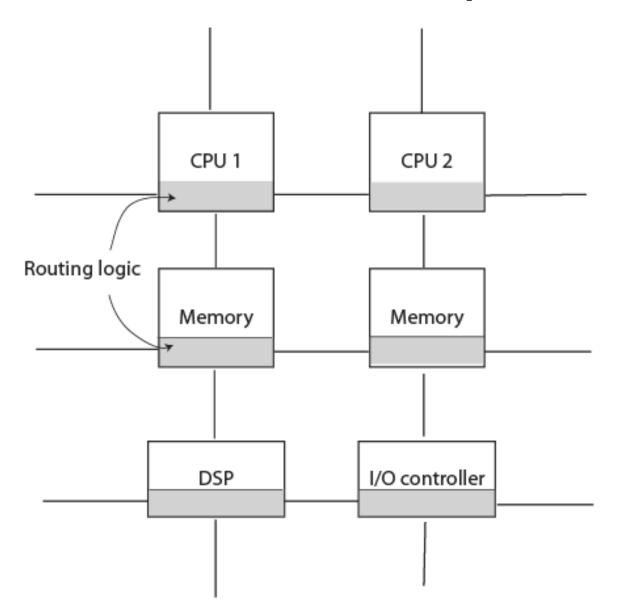
SOC interconnect

- interconnecting multiple active agents requires
 - bandwidth: capacity to transmit information (bps)
 - protocol: logic for non-interfering message transmission
- bus
 - AMBA (adv. Microcontroller bus architecture) from ARM, widely used for SOC
 - bus performance: can determine system performance
- network on chip
 - array of switches
 - statically switched: eg mesh
 - dynamically switched: eg crossbar

Bus based SOC



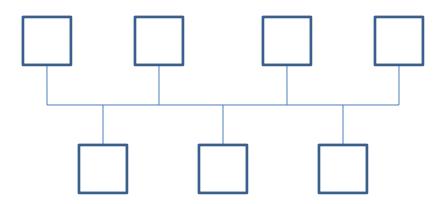
Network on a Chip



Networks-on-Chip (NoCs)

Motivation

- Bus has been the most popular interconnect for multiprocessor systems
- When scaling feature sizes and frequency, wire delays remain larger than clock cycle
- When expanding to a many core-system, contention decreases throughput



Need for interconnect with deterministic delays and scalability

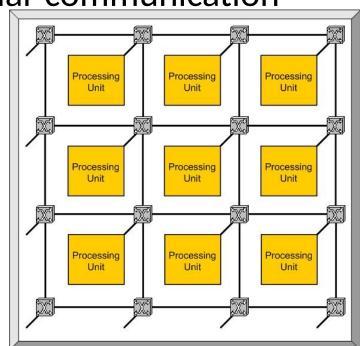
What is a Network-on-Chip (NoC)?

 Leveraging existing computer networking principles to improve inter-component intra-chip communications

 Each on-chip component connected by an intelligent switch to particular communication

wire(s)

 Improvement over standard bus based interconnections for SoC architectures in terms of throughput



Networks on chip: advantages

differentiated services

offer different kinds of communication with one network

scalable

 add routers and network interfaces for extra bandwidth (at the cost of additional latency)

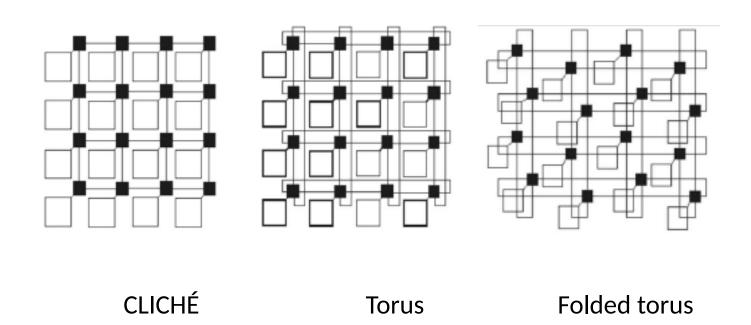
compositional

add routers/NIs without changing existing components
 e.g. timing, buffers

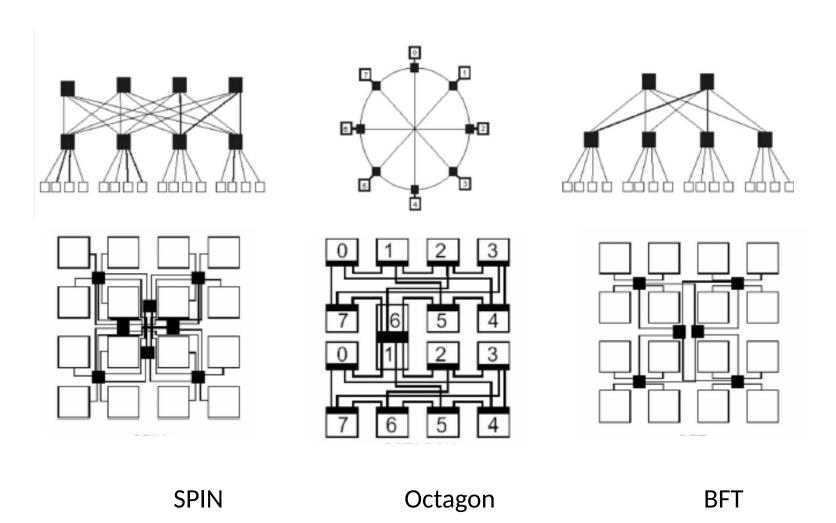
efficient use of wires

- statistical multiplexing/sharing (average vs. worst-case)
 - \Rightarrow fewer wires \Rightarrow less wire congestion
- point to point wires at high speed
- communication becomes re-usable, configurable IP

Topologies



Topologies contd.





Dedicated Wiring	On-Chip Network
Spaghetti wiring	Ordered wiring
Variation makes it hard to model crosstalk, returns, length, R & C.	No variation, so easy to exactly model XT, returns, R and C.
Drivers sized for 'wire model' – 99% too large, 1% too small	Driver sized exactly for wire
Hard to use advanced signaling	Easy to use advanced signaling
Low duty factor	High duty factor
No protocol overhead	Small protocol overhead

Switching

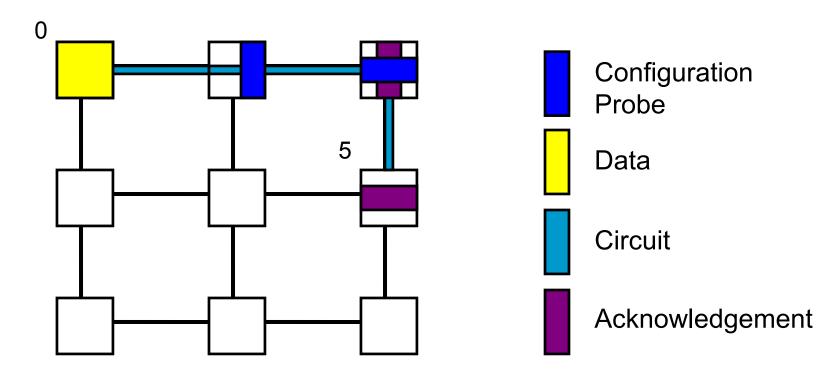
Circuit Switching

- Dedicated path, or circuit, is established over which data packets will travel
- Naturally lends itself to time-sensitive guaranteed service due to resource allocation
- Reservation of bandwidth decreases overall throughput and increases average delays

Packet Switching

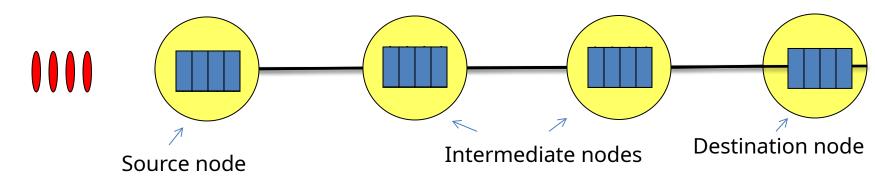
- Intermediate routers are now responsible for the routing of individual packets through the network, rather than following a single path
- Provides for so-called best-effort services
- Sharing of resources allows for higher throughput

Circuit Switching Example



- Significant latency overhead prior to data transfer
- Other requests forced to wait for resources

Store & Forward Switching

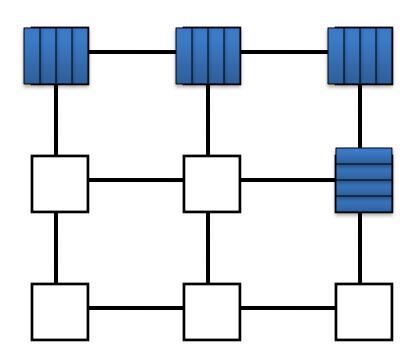


- Each node along a route waits until a packet is completely received (stored) and then the packet is forwarded to the next node
- Two resources are needed
 - Packet-sized buffer in the switch
 - Exclusive use of the outgoing channel

Store & Forward Switching

- S&F switching forwards a packet only when there is enough space available in the receiving buffer to hold the entire packet.
- Thus, there is no need for dividing a packet into flits. This
 reduces the overhead, as it does not require circuits such
 as a flit builder, a flit decoder, a flit stripper and a flit
 sequencer.
- Nevertheless, such a switching technique requires a large amount of buffer space at each node. Thus, it may not be a feasible solution for embedded applications

Store & Forward Switching Example



- High per-hop latency
- Larger buffering required

Store & Forward Switching

- Finer grained sharing of the link bandwidth
- Routing, arbitration, switching overheads experienced for each packet
- Increased storage requirements at the nodes
- Packetization and in-order delivery requirements
- Alternative buffering schemes
 - Use of local processor memory
 - Central (to the switch) queues

Switching contd.

Wormhole Switching

- Message is divided up into smaller, fixed length flow units called flits
- Only first flit contains routing information, subsequent flits follow
- Buffer size is significantly reduced due to the limitation on the number of flits needed to be buffered at any given time

Virtual Channels

- Allows for several instances of wormhole switching
- Additional buffers are added, which increases overall switch size, but significantly increases throughput

Performance Metrics

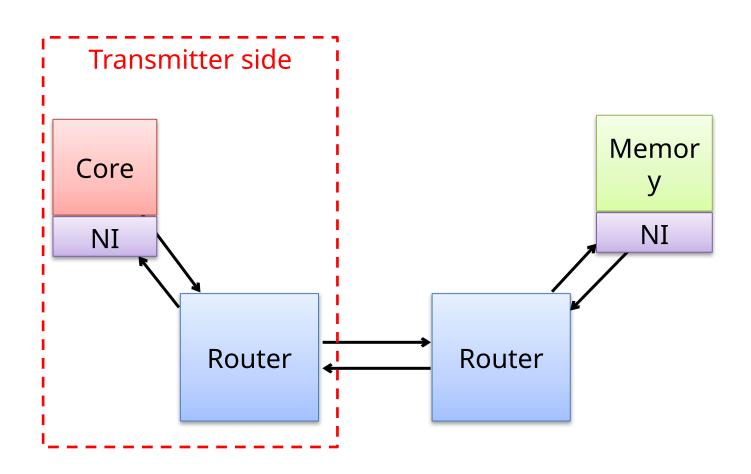
Simulator developed to measure:

- Throughput (in flits)
- Latency (of flits)
- Energy (per packet)

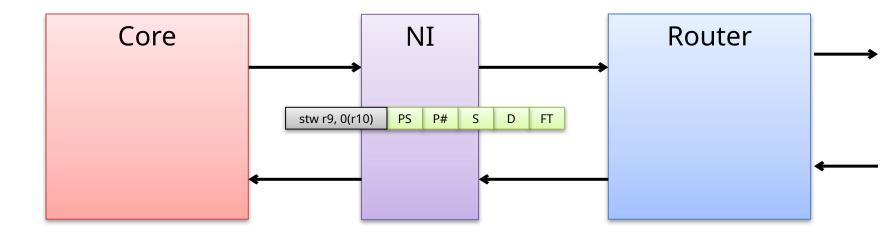
Hardware model developed to estimate:

Area (router and link overhead)

Network Interface



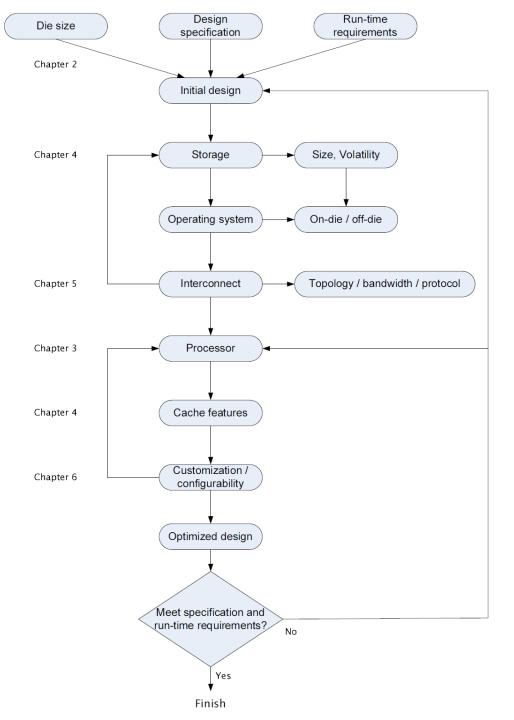
Network Interface



SOC design approach

- understand application (compiler, OS, memory and real time constrains)
- select initial die area, power, performance targets;
 select initial processors, memory, interconnect
- assume target processor and interconnect performance, design and evaluate memory
- evaluate and redesign processors with memory
- design interconnect to support processors and memory
- repeat and iterate to optimize

SOC design approach



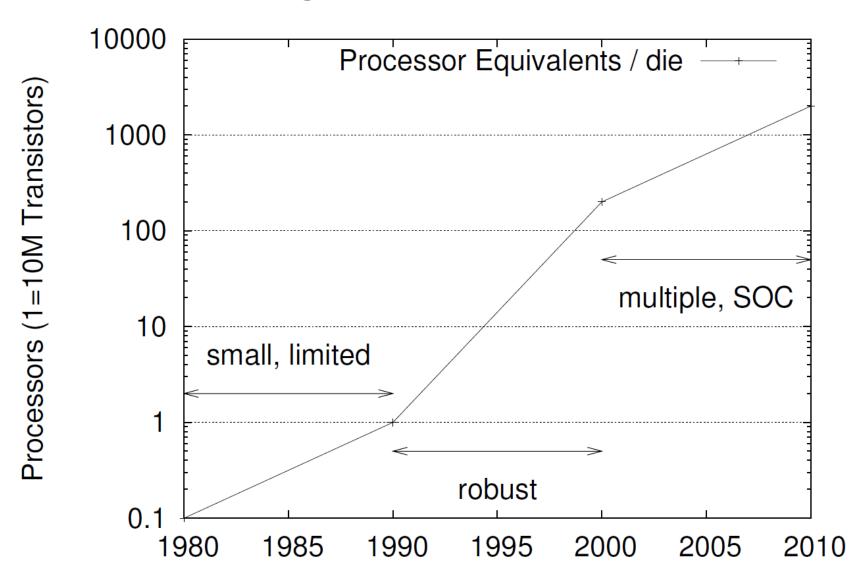
Processor optimization example

- given embedded ARM processor
 - in an SOC chip
- 1 IALU vs 2 IALU vs 3 IALU vs 4 IALU
 - instructions per cycle?
- 16k L1 instruction cache vs 32k L1 i-cache
 - how much improvement? less power?
- branch predictor: taken vs not-taken
 - misprediction rate?
- aim: explore this large design space

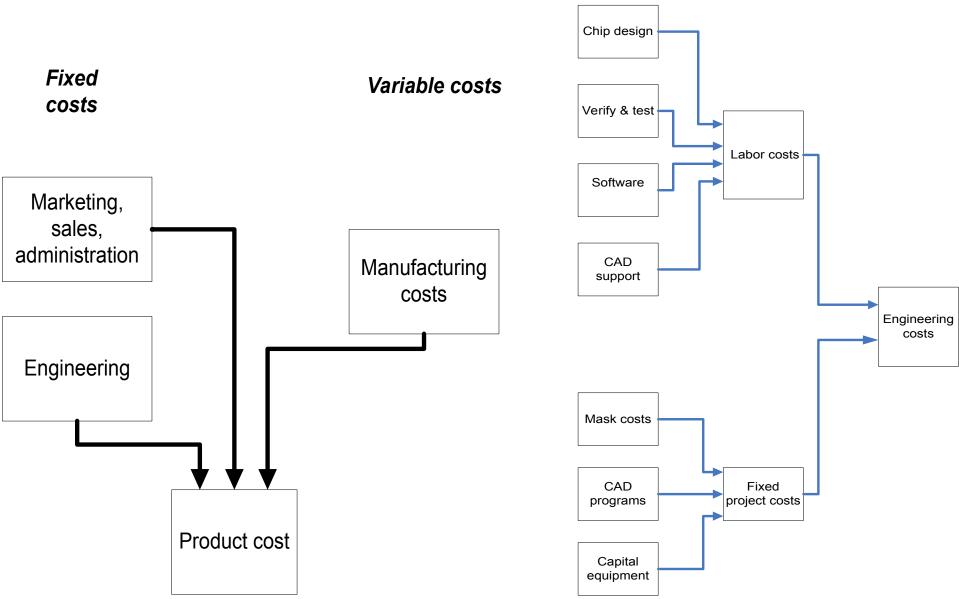
Design cost: product economics

- increasingly product cost determined by
 - design costs, including verification
 - not marginal cost to produce
- manage complexity in die technology by
 - engineering effort
 - engineering cleverness

Design complexity



Cost: product program vs engineering



Product volume dictates design effort

Design time and effort

Basic physical tradeoffs



Balance point depends on n, number of units

Summary

- to design and evaluate an SOC, designers need to understand:
 - its components: processors, memory, interconnect
 - applications that it targets
- SOC economics heavily dependent on:
 - costs: initial design, marginal production
 - volume: applicability, lifetime
- reducing design complexity
 - Intellectual Property (IP)
 - reconfigurable technology

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